

# Prototyping: Considerations From the Bread Board for the Final Product

A. Jensen Newman, Ph.D., EIT

Principal Investigator: Power, Energy, Controls, and Electronics UT Dallas Applied Research Center 716-544-3184 ajn160130@utdallas.edu **Prepared For:** 

**DFW Sensor & IoT Technology Meetup** 

Background Image: TRL8 Energy Saving Control Unit Developed by Newman et al.

### **Outline**

- About Me
- If I Could Only Tell You 2 Things...
- Breadboarding The First Step
- Circuit Design/Schematic Capture
- PCB Design
- Final Assembly
- Free Tools
- Design For Manufacture

#### **About Me**

#### **Education**

- Ph.D. Applied Mathematics, RPI 2013
- M.S. Mechanical Engineering, UB 2010
- B.T. Electrical Eng. Tech., Buff. State 2008
- B.T. Mechanical Eng. Tech., Buff. State 2007
- A.A.S. Drafting Tech., ECC 2005

#### **Professional**

- UTD ARC Principal Investigator
- Applied Research Associates –
- Group Leader
- Cameron Compression Designer
- ATSI Piping Engineer













#### These are a Few of My Recent Projects





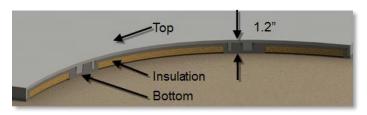


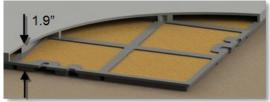
Multi-Functional Transcranial Electrical Stimulation System





**Energy Savings Control Unit** 







Energy Efficient Expeditionary Flooring



#### If I Could Only Tell you Two Things... (1)





#### If I Could Only Tell you Two Things... (2)





LT1637 1.1MHz, 0.4V/us

Over-The-Top Micropower, Rail-To-Rail Input and Output Op Amp

#### **FEATURES**

- Operates with Inputs Above V+
   Rail-to-Rail Input and Output
- Micropower: 250µA Supply Current Max Operating Temperature Range: -55°C to 125°C
- Gain-Bandwidth Product: 1.1MHz
- Slew Rate: 0.4V/μs
   Low Input Offset Voltage: 350μV Max
- Single Supply Input Range: -0.4V to 44V
- High Output Current: 25mA Min
- Specified on 3V, 5V and ±15V Supplies
- Output Drives 4700pF with Output Compensation
- Reverse Battery Protection to 25V
- High Voltage Gain: 800V/mV
- High CMRR: 110dB
- Available in 8-Lead MSOP, PDIP and SO Packages; and a Tiny (3mm × 3mm × 0.8mm) DFN Package

#### **APPLICATIONS**

- Battery or Solar Powered Systems: Portable Instrumentation
- Sensor Conditioning Supply Current Sensing
- Battery Monitoring
- MUX Amplifiers
- 4mA to 25mA Transmitters

#### DESCRIPTION

The LT®1637 is a rugged op amp that operates on all single and split supplies with a total voltage of 2.7V to 44V. The LT1637 has a gain-bandwidth product of 1.1MHz while drawing less than 250µA of quiescent current. The LT1637 can be shut down, making the output high impedance and reducing the quiescent current to only 3µA. The LT1637 is reverse supply protected: it draws virtually no current for reverse supply up to 25V. The input range of the LT1637 includes both supplies and the output swings to both supplies. Unlike most micropower op amps, the LT1637 can drive heavy loads; its rail-to-rail output drives 25mA. The LT1637 is unity-gain stable into all capacitive loads up to 4700pF when optional  $0.22\mu F$  and  $150\Omega$  compensation is used.

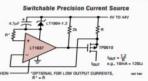
The LT1637 has a unique input stage that operates and remains high impedance when above the positive supply. The inputs take 44V both differential and common mode, even when operating on a 3V supply. Built-in resistors protect the inputs for faults below the negative supply up to 22V. There is no phase reversal of the output for inputs 5V below VEE or 44V above VEE, independent of VCC.

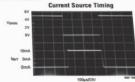
The LT1637 op amp is available in the 8-pin MSOP, PDIP and SO packages. For space limited applications, the LT1637 is available in a 3mm × 3mm × 0.8mm dual fine pitch leadless package (DFN).

CT, LT, LTC and LTM are registered trademarks of Linear Technology Cor Over-The-Top is a registered trademark of Linear Technology Corporation All other trademarks are the property of their respective owners.

#### TYPICAL APPLICATION

Over-The-Top® Current Source with Shutdown

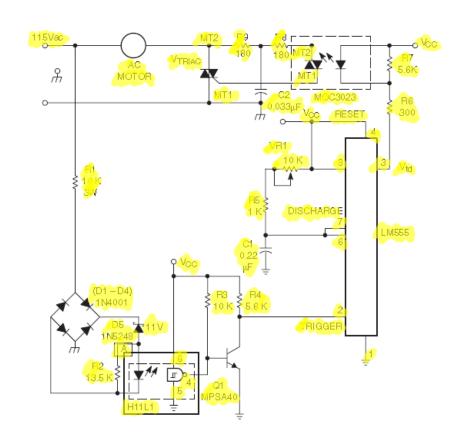






#### If I Could Only Tell you Two Things... (2)

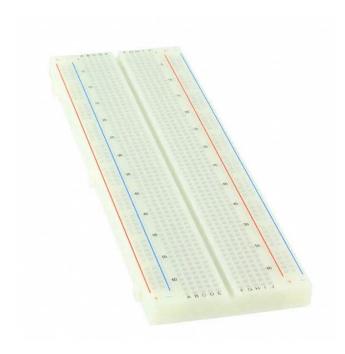




You Will Check. The Only Question is: Do You Check Before or After Something Breaks?



## Breadboarding



#### Always Use an ESD Wrist Strap





**Digikey PN** 

16-1087-ND

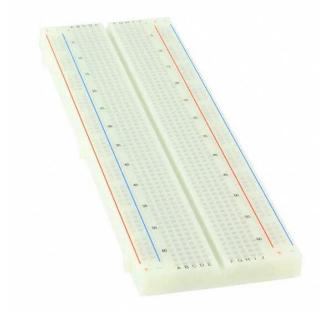
You will not always see a spark if an ESD event occurs



## **Knowing these Breadboard Specs Will Help You Pick the Right Parts**

DALLAS
Applied Research Center

- 100 mil pitch
- Center is 300 mil pitch
- 1.5 A capacity
- Look for parts with lead dia. < 40 mil, length</li>
   >=138 mil (3.5mm)



**Digikey PN** 

BKGS-830-ND



## **Use Wire to Board Terminal Blocks If Connecting to Breadboard**







Item	Digikey PN
15A 12-30 AWG	277-5911-ND
10A 14-30 AWG (low profile)	277-6270-ND

Rising Edge Cage Clamp



## Look for Parts Available in Both DIP and SMT



Compare Parts	7	lmage	Digi-Ke Nun	ey Part nber	Manufa Part N		Manufa	acturer	Desci	ription	Quar Availa	able	Unit P US	D	Minir Quar	ntity	Pack	aging	Packag	e / Case	Dev	plier vice kage
			<b>A</b>	_	<b>^</b>	▼	_	_	_		<b>A</b>	•		~	•	~	_	_	<b>A</b>	•	<b>A</b>	_
	7	reditter.	ADG436	BRZ-ND	ADG4361	<u>BRZ</u>	Analog Device		IC SWITCH SPDT 16S		890 - Immedi	iate	6.9000	00	1		Tube Alterna Packa	ate	16-SOIC 3.90mm		16-SOI	С
			ADG436	BNZ-ND	ADG4361	BNZ	Analog Device		IC SWITCH SPDT 16D		133 - Immedi 2,500 - Factory Stock		7.4700	00	1		Tube	3	16-DIP (( 7.62mm)		16-PDI	P

Common SMT Packages
SOIC
SWD
QFN
TSSOP
1206

Double Check Your Packaging and Footprints

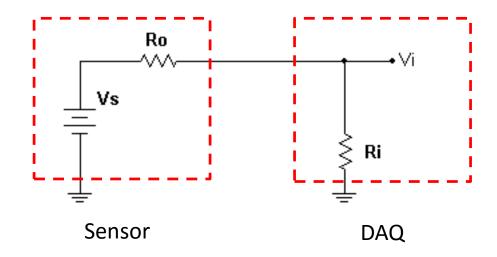
DIP: Dual In-Line
Plastic
SMT: Surface Mount
Technology

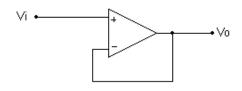
**Avoid Plastic Ball Gated Array (PBGA)** 



## Watch out for Low Input Impedances; Avoid Sensors That Output Voltage







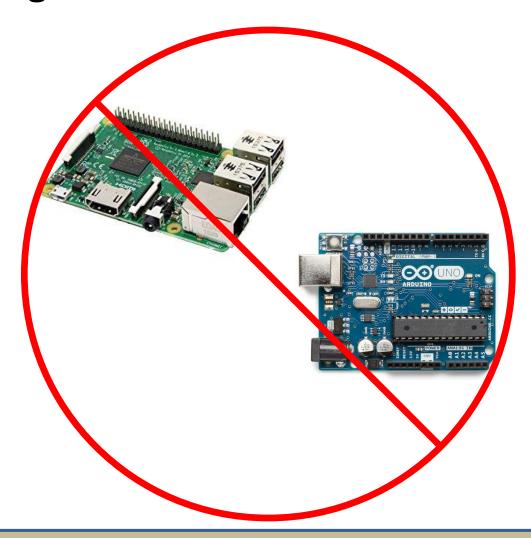
Voltage Follower

Voltage is Follower is one of My Favorite Circuits; Output Z:Input Z = 1:100



## **Avoid Raspberry Pi or Arduino if Trying** to Bring a Product to Market





Not Available at MFG Quantities. You Will Have to Port

#### **General Breadboarding Guidlines**

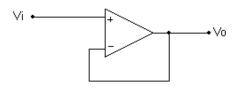


- Avoid Touching Breadboard/Prototypes When Power is On (Even if it is low voltage)
- Set up your measurements first, then power on
- Switch off and unplug
- Order more parts than you need



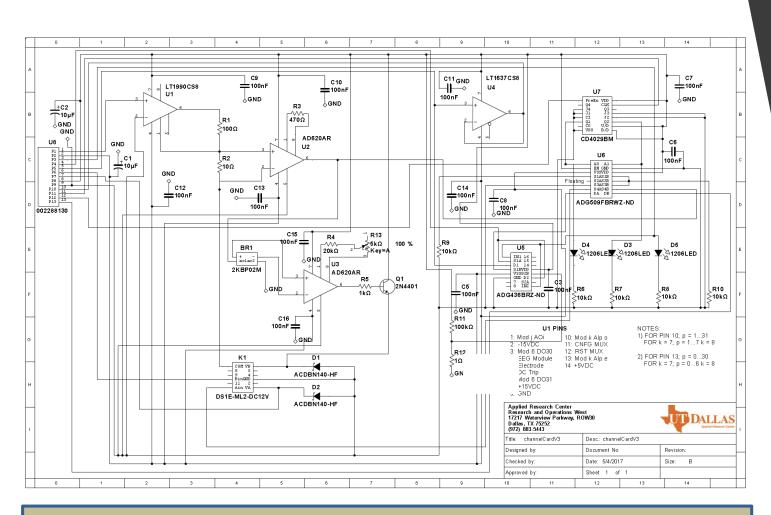


# Circuit Design/Schematic Capture



## **Use Named Nets Instead of Wires on Schematics**

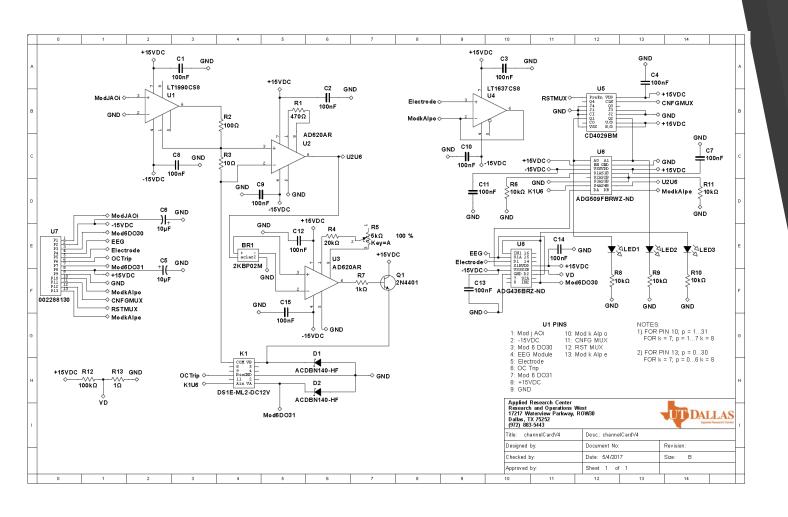






## **Use Named Nets Instead of Wires on Schematics**



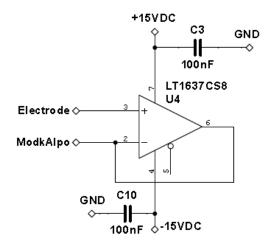




## Bypass Caps Prevent Damage, and Ensure Proper IC Operation

DALLAS
Applied Research Center

- Every IC gets one
- Dual voltage IC's get two



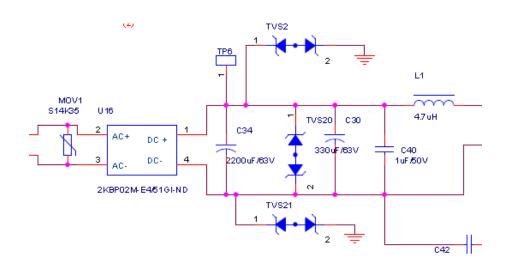
Item	Digikey PN
10 uF Tantalum Cap	PN 399-5152-1-ND
0.1 uF Ceramic Cap	399-1249-1-ND











Item	Digikey PN
TVS Diode	296-41842-1-ND
Choke	PM3700-70-RCCT-ND

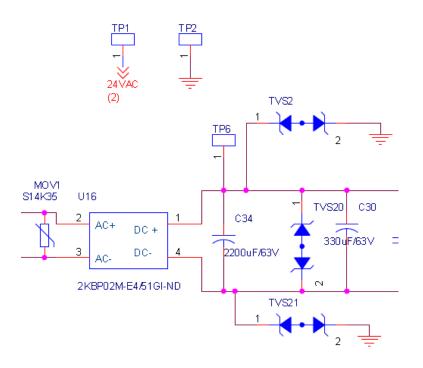


Good Practice in Prototyping Too



## You can Never Have Too Many Test Points





Especially ground points (you want to avoid making large loops with scope cables)



## Provide Jumpers to Ground JTAG Lines, Especially Clock, When Using MCUs



Define JTAG



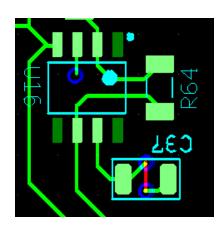
**Digikey PN** 

S3404-ND



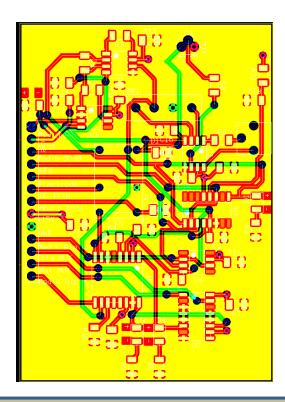


### PCB Design



#### **Always Use Copper Planes**

- At Least Two One for Vdd and one for VSS
- Do Not run Copper Planes to Edges



If using a 4 layer board make the two internal layers power and ground plane – No signals on internal layers

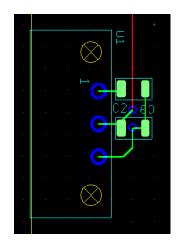


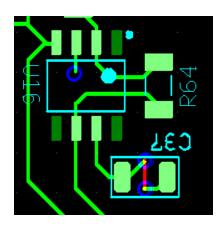


## By-Pass Caps Should be as Close to IC's/Power Entry as possible

DALLAS
Applied Research Center

- Every IC gets one
- Dual voltage IC's get two



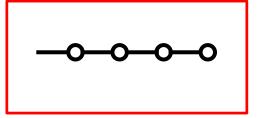


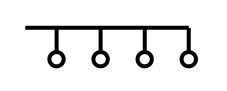
Item	Digikey PN
10 uF Tantalum Cap	PN 399-5152-1-ND
0.1 uF Ceramic Cap	399-1249-1-ND



## **Avoid Routing Traces Through Mounting Holes/Pads**







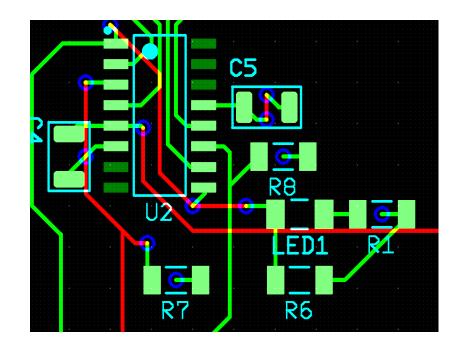
No.
Removing one pad requires
two cuts and a bridge.
Also, Trace and pads act like a
heat sink – harder to solder.

Yes.
Removing one pad requires one cut.



## **Avoid Placing Vias Under ICs, Esp. For Reflow**



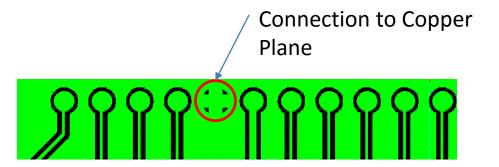


Solder can Bridge and You Will Not Know



## Make Sure Copper Plane Connections Have Thermal Relief



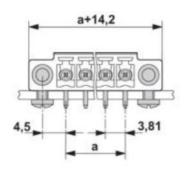




## **Use Connectors When Connecting Wires to PCB**









Item	Digikey PN
Male	277-5764-ND
Female	277-5714-ND

**Require No Special Tools** 



#### These Are Some General PCB Guidelines



- Use double sided board with power and ground planes on top and bottom
- Use Informative Silkscreen Labels Excessively
- If using a 4 layer board make the two internal layers power and ground plane – No signals on internal layers
- Use plated holes connected to ground for mounting holes watch your screw head size though (remember key takeaway #2)
- Hole diameter = 40 mils
- Track width = 10-60 mils (10 mil traces with 10 mil spacing is a good one, beef up any power traces)
- Circular pads = 80-120 mils
- Width/height for rectangular pads = 80-120 mils





## **Final Assembly**



## ALWAYS clean your PCB with Alcohol First





**Digikey PN** 

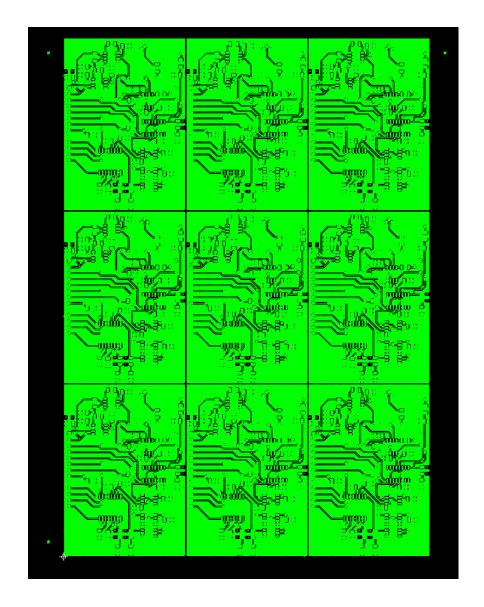
473-1150-ND

Don't Touch it After You Clean It. Handle Like a Record



#### For Multiple Boards Consider Panelizing







#### These are Some Good Solder Choices



- 63/37 RA/RMA for hand soldering
- 42/57.6/0.4 for Reflow Soldering

Item	Digikey PN
63/37 Solder Wire	KE1400-ND
42/57.6/0.4 Solder Paste	SMDLTLFP-ND

Weld	T (deg C)	Minutes
Pre-heat	100	1
Heat	150	1
Melt	170	0.5
Cool	170	-

This Profile Works Well for 42/57.6/0.4 with Single Chamber Reflow Ovens

Always Store Solder Paste in the Fridge, Remove 24 Hours Before Use



#### **Some Final Comments on ASSM**

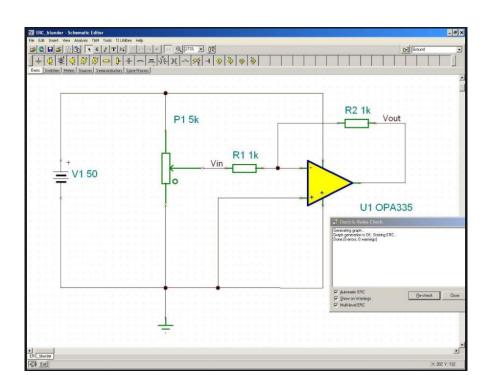


- You can use conformal coating to "seal" your board after it has been soldered. Protects agains condutction and moisture
- Watch your packaging when ordering – reals are a pain if not using P and P





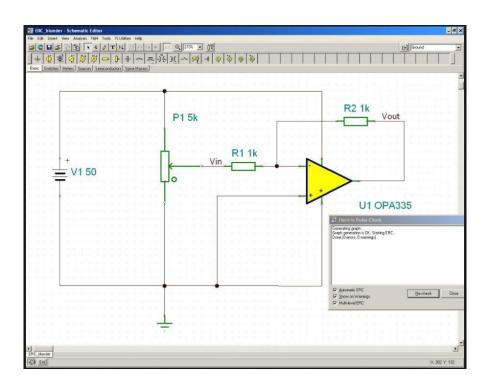
#### **Free Tools**



## TINA is a Free SPICE-based Analog Simulation Program



- DC, Transient & Frequency Analysis
- Virtual Tools Including Oscope and Probes



http://www.ti.com/tool/tina-ti



# Webench is an Online Design Tool Power, Lighting, Filtering, Clocking and Sensing Circuits



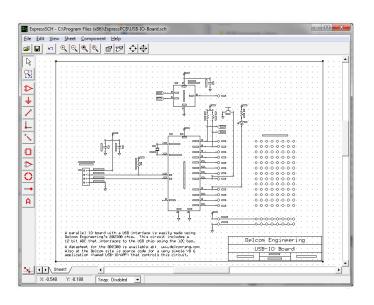
:H® Des	<i>My</i> Desig			
Sensors	Interface	Reference		
FPGA/µP	LED	Clocks		
ency	Output F	requency		
MHz	24	MHz		
	27	MHz		
	25	MHz		
ons	Star	t Design		
	Sensors FPGA/μP	ency Output F  MHz 24  27  25		

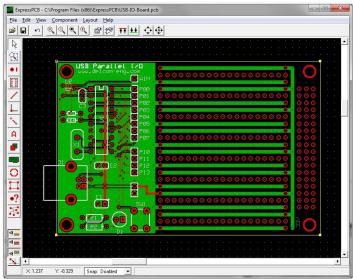
http://www.ti.com/lsds/ti/analog/webench/overview.page



# Express PCB is A PCB MFG That Makes Cheap Boards, Provided They're Designed with Their Tool







https://www.expresspcb.com/free-cad-software/



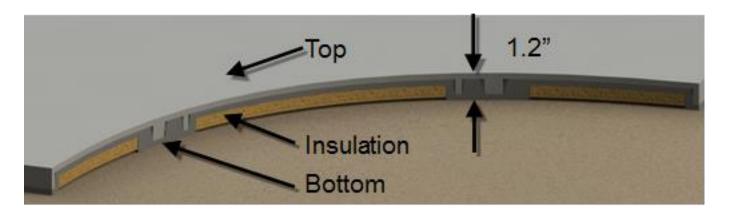


### Design For Manufacture



## Make sure you have fillets, drafts, clearances, tolerances







Gemini Plastics, Inc. is a great plastic manufacturer

<a href="http://www.gplastics.com/index.html">http://www.gplastics.com/index.html</a>

Jeremy O'Connell 920-336-2525

joconnell@gplastics.com

Communicate with your potential manufacturer ahead of time to get a sense of what their tools can and cannot do





## These are My Best Practices

Your best practices depend on what you do, in your work there are elements just like this.

Think through your work process to save yourself time and money



### Questions?